低溶劑增層膜接著材料

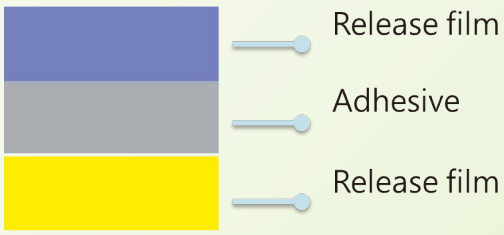
Low-Solvent Build-Up Film Adhesive Material

隨AI伺服器、5G及先進封裝需求提升，產業亟需發展高固含、低溶劑、低離子遷移之國產增層接著材料，以提升材料利用效率與供應鏈自主性。

As demand for AI servers, 5G communications, and advanced packaging continues to grow, there is an urgent need to develop domestically produced build-up adhesive materials featuring high solids content, low solvent content, and low ion migration, in order to improve material utilization efficiency and strengthen supply-chain self-reliance.

技術特色

- 低極性 Low polarity
- 低損耗 low dielectric loss
- 高接著 high adhesion strength
- 高交聯穩定性 high crosslinking stability
- 低氯低碳 low chlorine content and low carbon footprint
- 優異加工性 excellent processability



低溶劑增層膜接著材料
Low-Solvent Build-Up
Film Adhesive Material

解決方案/應用案例

本技術透過改質可溶型聚酯、低氯低碳環氧樹脂及Low Dk/Df PPE整合，將每單位塗料有效使用率由約30%提升至61%以上，並兼具低溢膠、高接著及1000小時 Ion migration 可靠度。此技術有助於降低原料與溶劑耗用、減少製程負擔，並建立國內自主之高頻低損耗增層接著材料技術。

This technology integrates modified soluble polyester, low-chlorine and low-carbon epoxy resin, and low-Dk/Df PPE to increase the effective utilization of the coating formulation from approximately 30% to over 61%, while simultaneously achieving low resin flow, high adhesion strength, and 1,000-hour ion-migration reliability. This approach helps reduce raw-material and solvent consumption, lessen processing burdens, and establish a domestically developed high-frequency, low-loss build-up adhesive material technology.

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